



# 100% Material Declaration Data Sheet FG676

PK155 (v1.2) September 25, 2006

Material Declaration Data Sheet

**Average Weight: 3.0620 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.1421</b>	<b>4.64%</b>
	Silicon	7440-21-3	100.00		0.1421	
<b>Die Attach Material</b>					<b>0.0124</b>	<b>0.40%</b>
	Silver	7440-22-4	78.00		0.0097	
	Resin	Trade Secret	22.00		0.0027	
<b>Mold Compound</b>					<b>1.0269</b>	<b>33.54%</b>
	Epoxy Resins	Trade Secret	12.00		0.1232	
	SiO2	60676-86-0	88.00	Filler	0.9037	
<b>Laminate</b>					<b>1.1419</b>	<b>37.29%</b>
	Laminate	Trade Secret	49.15		0.5613	
	Solder Mask	Trade Secret	7.69		0.0878	
	Copper	7440-50-8	40.83	Metal Layer	0.4662	
	Nickel	7440-02-0	1.95	Metal Layer	0.0223	
	Gold	7440-57-5	0.38	Metal Layer	0.0043	
<b>Bond Wire</b>					<b>0.0235</b>	<b>0.77%</b>
	Gold	7440-57-5	99.00		0.023302516	
	Silver	7440-22-4	0.0025		0.00000588	
	Copper	7440-50-8	0.0005		0.00000118	
	Iron	7439-89-6	0.0005		0.00000118	
	Calcium	7440-70-2	0.0020		0.00000471	
	Palladium	7440-05-3	0.9900		0.000233025	
	Magnesium	7439-95-4	0.0005		0.00000118	
<b>Solder Balls</b>					<b>0.7153</b>	<b>23.36%</b>
	Tin	7440-31-5	63.00		0.450639	
	Lead	7439-92-1	37.00		0.264661	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
6/15/06	1.1	100% Material Declaration.
9/25/06	1.2	Updated component descriptions.